

Mini USB Connectors

Description:

Board mount I/O connectors for the industry standard USB (Universal Serial Bus) interface used to connect high speed peripheral devices to computers. Mini USBs are ideal for applications that require small, light-weight connectors.

Typical Applications:

- Desktop and notebook computers
- PDAs, cell phones
- Portable music recorders/players
- Digital cameras
- External disk drives

Benefits/Features:

- Industry Standard Meets the speed requirements of USB 2.0.
Meets preliminary requirements of USB OTG (On-The-Go).
- Flexible System SMT and through hole mounting styles are available.
Allows for hot plugging of multiple devices.
- Ruggedness and Reliability Full metal shields help protect contacts from physical and ESD (Electro Static Discharge) damage.
High cycle life versions are available.

Selectable Features:

| | |
|-------------------------|---|
| Product Type | Mini-B USB receptacles |
| Total No. of Positions | 5 |
| Centerline Spacing | 0.8 mm [.0315 in.] |
| Orientation | Horizontal |
| Mounting Style | DIP or SMT |
| Operating Voltage | 30 VAC RMS |
| PCB Thickness | SMT: N/A TH: 0.8 mm [.0315 in.] |
| Contact Style | Formed |
| Contact Area Plating | Gold-plated (see product print for thickness) |
| Height Above Board | 4 mm [.16 in.] |
| Shell (Shield) Material | Brass |
| Housing Color | Black |

Other Properties:

| | |
|------------------------------|---|
| Packaging Type | SMT: tape and reel, Through hole: tray |
| Housing Material | Nylon GF |
| Applicable Soldering Process | IR, vapor phase, wave |
| Contact Base Material | Phosphor bronze |
| Insulation Resistance | 100 M Ω initial |
| Withstanding Voltage | 100 VAC RMS |
| Current Rating | 1 amp max. per contact |
| Contact Resistance | 30 m Ω |
| Temperature Range | -25°C to +70°C |
| Normal Force | 30 g min. (controlled by cable connector) |
| Durability (Mating Cycles) | 5000 cycles |
| Mating Force | 35 N [7.9 lbf] max. |
| Unmating Force | 7 N [1.6 lbf] min. initial |
| Plating (Contact Area) | Gold (thickness varies per Delphi spec.) over nickel underplating |
| Plating (Soldering End) | 2.03 μ m [80 μ in.] min. tin-lead over nickel underplating |
| Plating (Shield) | 2.03 μ m [80 μ in.] min. tin-lead over nickel underplating |
| Underplating | 1.27 μ m [50 μ in.] nickel |
| Standards | Universal Serial Bus Revision 2.0 specification USB 2.0 Specification ECN #1: Mini-B connector |
| Approvals and Certification | UL approved |



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Ordering Nomenclature

1543 0383 - 1 0 0

Surface Mount . . . **1543 0383**
Through Hole **1543 0384**

Selective Plating:

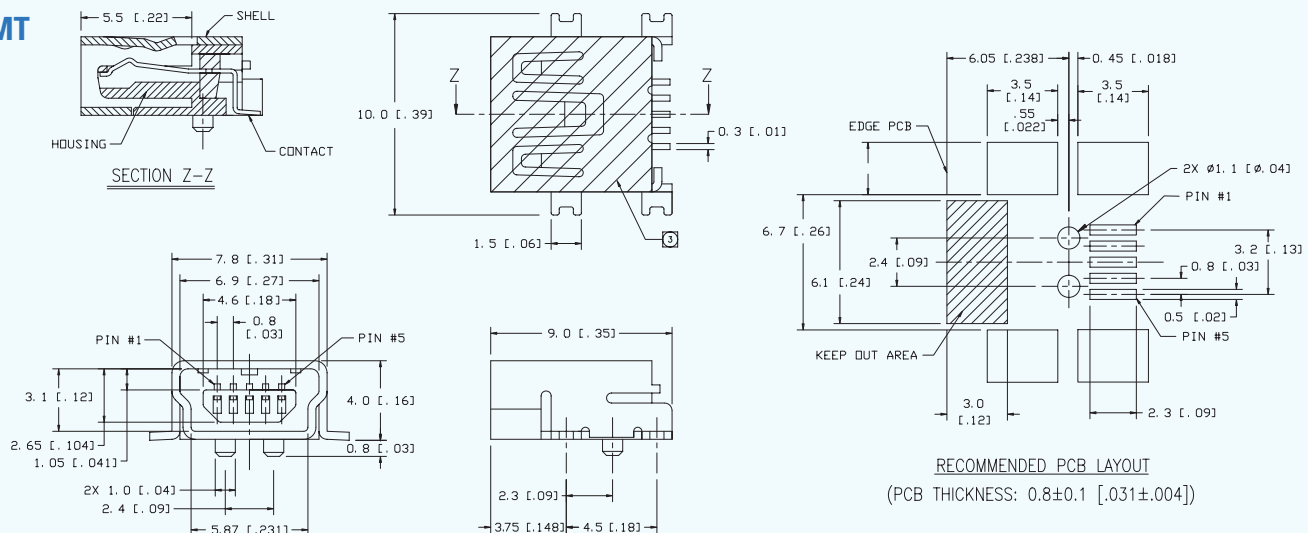
Gold plated on contact area and 2.54 µm [100 µin.] min. tin-lead plated on soldering end over 1.27 µm [50 µin.] min. nickel underplating

1 = Gold Flash

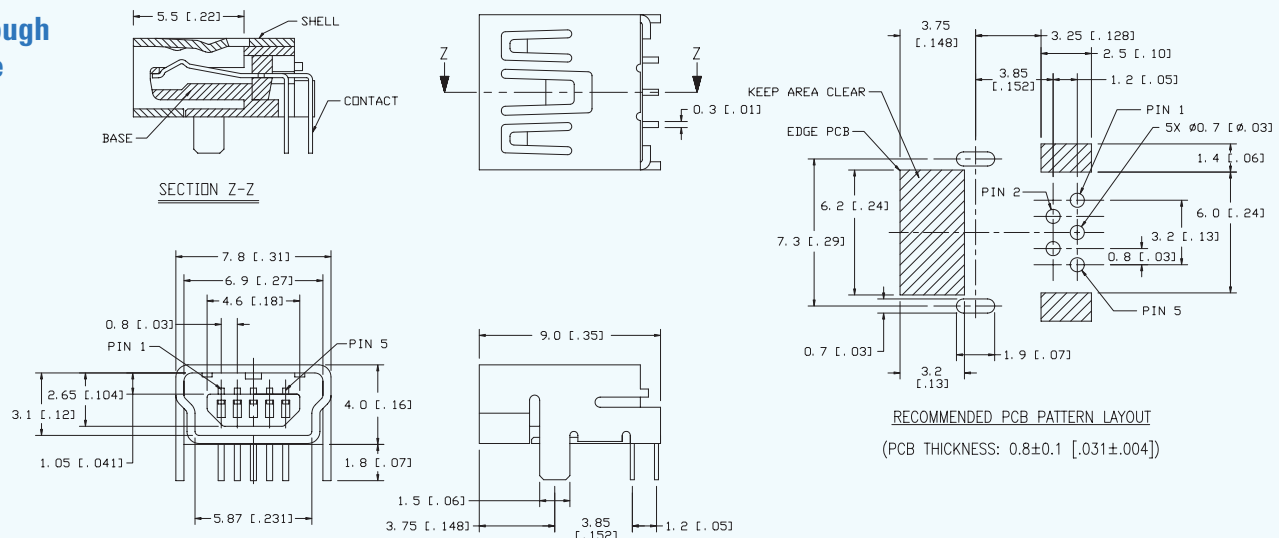
2 = 0.381 µm [15 µin.]

3 = 0.762 µm [30 µin.]

SMT



Through Hole



Dimensions are shown in millimeters [inches].

DELPHI

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www.delphi.com/connect

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Printed in the U.S.A.
DP-02-E-066 702/3W

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